*OPTICAL EPOXY RESINS, GLOB TOP, STRUCTURAL BONDING - ONE-COMPONENT**

REF	CURONG SCHEDULE Recommended	POT LIFE After mixing	VISCOSITY	Tg	DEGRADATION	FILLER	THERMAL EXPANSION		RESISTIVITY	COMMENTS
							BEFORE TG	AFTER TG		
E506	1 min at 125°C	3 days at 4°C	0,4 Pa.S	80-90°C	350-360°C		60-70.10^{-6}/°C	140-160.10^{-6}/°C	10^{13} Ω.cm	Chip protection smart cards - high purity
E506-5	1 h at 135°C	1 month at 20°C	12 Pa.S	120-135°C	370-390°C		60-80.10^{-6}/°C	170-190.10^{-6}/°C	10^{17} Ω.cm	Silicon chip protection - Black -High purity
E506-7	10 min at 100°C	5 h at 20°C	4 Pa.S	60-70°C	370-390°C		55-65.10^{-6}/°C	130-160.10^{-6}/°C	10^{13} Ω.cm	Silicon chip protection - High purity - High resistance to humidity
E507-3	5 min at 150°C	24 h at 25°C	22,5 Pa.S	160-170°C	350-370°C	72%	15-25.10^{-6}/°C	55-65.10^{-6}/°C	10^{13} Ω.cm	Chip protection smart cards
E508	5 min at 150°C	6 days at 20°C	70 Pa.S	145-155°C	> 350°C	75%	18-20.10^{-6}/°C	65-75.10^{-6}/°C	10^{13} Ω.cm	Chip protection smart cards - Recommended for large size chips
E508HV	5 min at 150°C	5 days at 20°C	130 Pa.S	145-155°C	> 350°C		23-25.10^{-6}/°C	85-100.10^{-6}/°C	10^{13} Ω.cm	Chip protection smart cards - Used to form a cordon of resin around the chip (dam)
E517	30 min at 150°C	1 month at 20°C	50 Pa.S	70-100°C	330-350°C		25-30.10^{-6}/°C	55-65.10^{-6}/°C	10^{13} Ω.cm	Silicon chip bonding and protection - High purity - Good thermal conductivity
E518FC	1 min at 150°C	8 h at 25°C	3,5 Pa.S	40-60°C	350-370°C	59%	30-40.10^{-6}/°C	100-110.10^{-6}/°C	10^{13} Ω.cm	Semiconductors protection Flip-chip technology
E519FC	1 min at 150°C	8 h at 25°C	3,5 Pa.S	40-60°C	350-370°C	64%	35-50.10^{-6}/°C	110-120.10^{-6}/°C	10^{13} Ω.cm	Semiconductors protection Flip-chip technology - UL94VO
NEA155	10 min at 150°C	4 months at 25°C	42 Pa.S	50-60°C	360-380°C	6%	90-100.10^{-6}/°C	180-200.10^{-6}/°C	10^{15} Ω.cm	Medium/high viscosity thixotropic paste for SMD - Red colour

* for more precision on the technical properties, to refer to the individual data sheet.

Maj 24/01/2007

épotecny

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